

## 6.40-7.20GHz 4-Watt Internally-Matched Power FET

### **FEATURES**

- 6.40-7.20GHz Bandwidth
- Input/Output Impedance Matched to 50 Ohms
- +36.5 dBm Output Power at 1dB Compression
- 9.5 dB Power Gain at 1dB Compression
- 36% Power Added Efficiency
- -46 dBc IM3 at PO = 25.5 dBm SCL
- 100% Tested for DC, RF, and R<sub>TH</sub>





### Caution! ESD sensitive device.

## **ELECTRICAL CHARACTERISTICS (T<sub>a</sub> = 25°C)**

SYMBOL	PARAMETERS/TEST CONDITIONS <sup>1</sup>	MIN	TYP	MAX	UNITS
P <sub>1dB</sub>	Output Power at 1dB Compression $f = 6.40-7.20GHz$ $V_{DS} = 10 \text{ V}, I_{DSQ} \approx 1100\text{mA}$	35.5	36.5		dBm
G <sub>1dB</sub>	Gain at 1dB Compression $f = 6.40-7.20GHz$ $V_{DS} = 10 \text{ V}, I_{DSQ} \approx 1100\text{mA}$	8.5	9.5		dB
ΔG	Gain Flatness $f = 6.40-7.20GHz$ $V_{DS} = 10 \text{ V}, I_{DSQ} \approx 1100\text{mA}$			±0.6	dB
PAE	Power Added Efficiency at 1dB Compression $V_{DS} = 10 \text{ V}, I_{DSQ} \approx 1100 \text{mA}$ f = 6.40-7.20GHz		36		%
Id <sub>1dB</sub>	Drain Current at 1dB Compression f = 6.40-7.20GHz		1100	1300	mA
IM3	Output 3rd Order Intermodulation Distortion $\Delta f = 10$ MHz 2-Tone Test; Pout = 25.5 dBm S.C.L <sup>2</sup> $V_{DS} = 10$ V, $I_{DSQ} \approx 65\%$ IDSS $f = 7.20$ GHz	-43	-46		dBc
I <sub>DSS</sub>	Saturated Drain Current $V_{DS} = 3 \text{ V}, V_{GS} = 0 \text{ V}$		2000	2500	mA
$V_P$	Pinch-off Voltage $V_{DS} = 3 \text{ V}, I_{DS} = 20 \text{ mA}$		-2.5	-4.0	V
R <sub>TH</sub>	Thermal Resistance <sup>3</sup>		5.5	6.0	°C/W

Note: 1. Tested with 100 Ohm gate resistor.

2. S.C.L. = Single Carrier Level.

3. Overall Rth depends on case mounting.

### ABSOLUTE MAXIMUM RATING FOR EFE

SYMBOLS	PARAMETERS	ABSOLUTE <sup>1</sup>	CONTINUOUS <sup>2</sup>	
Vds	Drain-Source Voltage	15V	10V	
Vgs	Gate-Source Voltage	-5V	-4V	
lgf	Forward Gate Current	48mA	14.4mA	
lgr	Reverse Gate Current	-9.6mA	-2.4mA	
Pin	Input Power	36dBm	@ 3dB Compression	
Tch	Channel Temperature	175C	175C	
Tstg	Storage Temperature	-65C to +175C	-65C to +175C	
Pt	Total Power Dissipation 25W		25W	

Note: 1. Exceeding any of the above ratings may result in permanent damage.

2. Exceeding any of the above ratings may reduce MTTF below design goals.

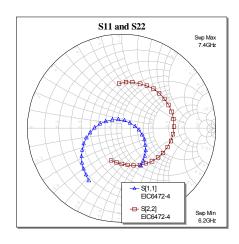


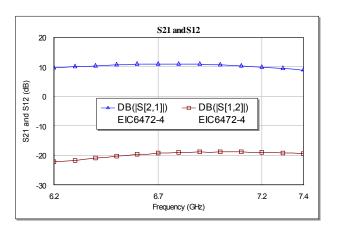


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### PERFORMANCE DATA

Typical S-Parameters (T= 25°C, 50 $\Omega$  system, de-embedded to edge of package) V<sub>DS</sub> = 10 V, I<sub>DSQ</sub>  $\approx$  1100mA





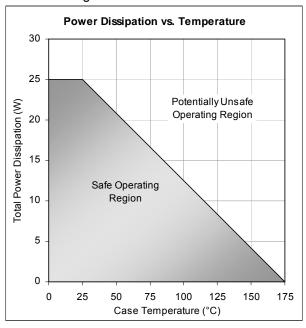
FREQ	S11		S21		S12		S22	
(GHz)	MAG	ANG	MAG	ANG	MAG	ANG	MAG	ANG
6.0	0.7446	-102.56	2.6955	-4.96	0.0623	-61.34	0.4238	127.4
6.2	0.6564	-122.03	3.0007	-31.42	0.0778	-87.4	0.4753	93.04
6.4	0.5197	-144.79	3.2845	-59.46	0.091	-116.15	0.5273	59.7
6.6	0.3381	-172.19	3.4917	-89.7	0.1042	-146.01	0.5579	26.43
6.8	0.1334	137.99	3.545	-121.42	0.1132	-176.76	0.5493	-6.3
7.0	0.1434	8.46	3.3891	-152.94	0.1165	153.37	0.4955	-38.82
7.2	0.3102	-35.87	3.1032	176.54	0.1127	123.35	0.4145	-72.21
7.4	0.4488	-63.26	2.7841	148.43	0.1073	94.96	0.3577	-108.03
7.6	0.5418	-88.96	2.4831	120.54	0.0965	66.98	0.3552	-148.1
7.8	0.5851	-112.49	2.1721	93.7	0.0875	40.86	0.4007	176.95
8.0	0.6041	-135.73	1.8779	68.06	0.0765	17.11	0.4693	151.21

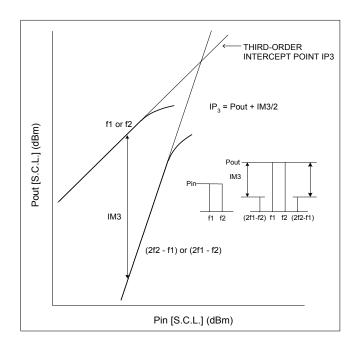




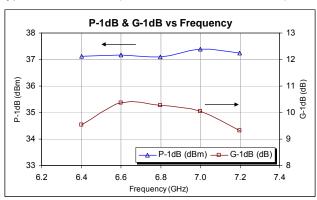
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### Power De-rating Curve and IM3 Definition

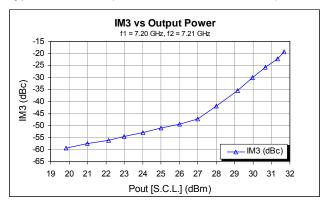




Typical Power Data (V<sub>DS</sub> = 10 V, I<sub>DSQ</sub> = 1100 mA)



Typical IM3 Data ( $V_{DS} = 10 \text{ V}$ ,  $I_{DSQ} \approx 65\% \text{ IDSS}$ )



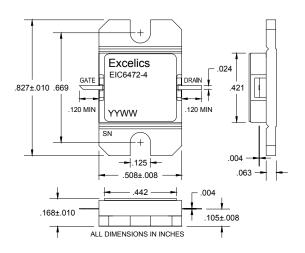


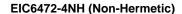
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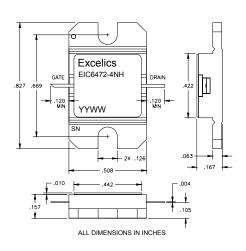
### **PACKAGES OUTLINE**

Dimensions in inches, Tolerance + .005 unless otherwise specified

### EIC6472-4 (Hermetic)









Caution! ESD sensitive device.



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### **ORDERING INFORMATION**

Part Number	Packages	Grade <sup>1</sup>	f <sub>Test</sub> (GHz)	P <sub>1dB</sub> (min)	IM <sub>3</sub> (min) <sup>2</sup>
EIC6472-4	Hermetic	Industrial	6.40-7.20GHz	35.5	-43
EIC6472-4NH	Non-Hermetic	Industrial	6.40-7.20GHz	35.5	-43

Notes:

- 1. Contact factory for military and hi-rel grades.
- 2. Exact test conditions are specified in "Electrical Characteristics" table.

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